L Number	Hits	Search Text	DB	Time stamp
1	0	ultraviolet adj atmospheric adj seed adj layer adj remediation	USPAT	2004/09/26 11:36
2	0	ultraviolet and housing and apparatus and ECD and medium and treatment and (seed adj layer adj remendation) and	USPAT	2004/09/26 11:39
3	0	contamination ultraviolet and apparatus and ECD and medium and treatment and (seed adj layer adj remendation) and	USPAT	2004/09/26 11:38
4	0	contamination ultraviolet and housing and apparatus and ECD and	USPAT	2004/09/26 11:38
		treatment and (seed adj layer adj remendation) and contamination		2004/20/20/11 70
5	0	ultraviolet and (seed adj layer adj remendation) and contamination	USPAT	2004/09/26 11:39
6	0	ultraviolet and housing and apparatus and ECD and medium and treatment and seed and remendation and contamination	USPAT	2004/09/26 11:40
7	0	ultraviolet and ECD and (plating adj bath) and seed	USPAT	2004/09/26 11:41
8	6	(ultraviolet adj radiation) and (treatment adj medium) and housing	USPAT	2004/09/26 11:42
9	6	((ultraviolet adj radiation) and (treatment adj medium) and	USPAT	2004/09/26 11:51
		housing) and (seed or layer or ECD or apparatus or oxygen or ozone or gas or pating or clean or bath or module or system or light or supply or ambinet or air or inlet or oxide or contaminants or medium or treatment or lamp)		
10	6	((ultraviolet adj radiation) and (treatment adj medium) and housing) and (seed or layer or ECD or apparatus or oxygen or ozone or gas or pating or clean or bath or module or	USPAT	2004/09/26 12:01
		system or light or supply or ambinet or air or inlet or oxide or contaminants or medium or treatment or lamp or substrate or wafer or semiconductor)		
11	1	("5078876").PN.	USPAT	2004/09/26 12:01
12	1	(("5078876").PN.) and (seed or layer or ECD or apparatus or oxygen or ozone or gas or pating or clean or bath or module or system or light or supply or ambinet or air or inlet or oxide or contaminants or medium or treatment or lamp or substrate or wafer or semiconductor)	USPAT	2004/09/26 12:02
13	. 1	l	USPAT	2004/09/26 12:02
14	1	(("4255383").PN.) and (seed or layer or ECD or apparatus	USPAT	2004/09/26 12:02
		or oxygen or ozone or gas or pating or clean or bath or module or system or light or supply or ambinet or air or inlet or oxide or contaminants or medium or treatment or lamp or substrate or wafer or semiconductor)		
15	1	("4317041").PN.	USPAT	2004/09/26 12:02
16	1	(("4317041").PN.) and (seed or layer or ECD or apparatus	USPAT	2004/09/26 12:03
		or oxygen or ozone or gas or pating or clean or bath or module or system or light or supply or ambinet or air or inlet or oxide or contaminants or medium or treatment or lamp or substrate or wafer or semiconductor)		
17	6	"4723420"	USPAT	2004/09/26 12:03
18	6	"4723420" and (seed or layer or ECD or apparatus or oxygen or ozone or gas or pating or clean or bath or module or system or light or supply or ambinet or air or inlet or	USPAT	2004/09/26 12:04
		oxide or contaminants or medium or treatment or lamp or		
19	ا ۵	substrate or wafer or semiconductor) "6099735"	USPAT	2004/09/26 12:04
20	4	l	USPAT	2004/09/26 12:04
		oxygen or ozone or gas or pating or clean or bath or module or system or light or supply or ambinet or air or inlet or		
		oxide or contaminants or medium or treatment or lamp or substrate or wafer or semiconductor)		
21	8	,	USPAT	2004/09/26 12:04

22	. 8	"6080313" and (seed or layer or ECD or apparatus or oxygen or ozone or gas or pating or clean or bath or module or system or light or supply or ambinet or air or inlet or oxide or contaminants or medium or treatment or lamp or	USPAT	2004/09/26 12:15
		substrate or wafer or semiconductor)		
23	1071	257/659	USPAT	2004/09/26 12:15
24	332	257/660	USPAT	2004/09/26 12:15
25	2356	257/678	USPAT	2004/09/26 12:16
26	206	257/682	USPAT	2004/09/26 12:16